



DMP3056L

30V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	RDS(ON) MAX	ID MAX Ta = +25°C
-30V	50mΩ @ V _{GS} =-10V	-4.3A
-30 V	70mΩ @ V _{GS} =-4.5V	-3.7A

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance $(R_{DS(ON)})$ yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

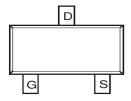
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Lead-Frame. Solderable per MIL-STD-202, Method 208 63
- Weight: 0.009 grams (Approximate)

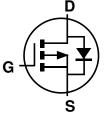




Top View



Top View Pin Configuration



Equivalent Circuit

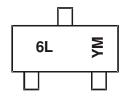
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3056L-7	SOT23 (Standard)	3000/Tape & Reel
DMP3056L-13	SOT23 (Standard)	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



6L = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: I = 2021) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2014		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	В			J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	-30	V
Gate-Source Voltage			V _{GSS}	±25	V
Drain Current (Note 5) V _{GS} = -10V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	ID	-4.3 -3.4	А
Pulsed Drain Current (Note 6)			I _{DM}	-20	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.38	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	91	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@ TA = +25°C, unless otherwise specified.)

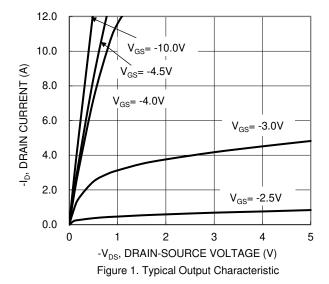
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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	IDSS		_	-1	μΑ	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	loop			±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
date-Source Leakage	lgss			±800	ш	$V_{GS} = \pm 25V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1	_	-2.1	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Drain-Source On-Resistance	RDS(ON)	_	35	50	mΩ	$V_{GS} = -10V, I_D = -6.0A$
Static Drain-Source On-Hesistance	NDS(ON)	_	50	70	1115.2	V _G S = -4.5V, I _D = -5.0A
Diode Forward Voltage	VsD	_	_	-1.2	V	Vgs = 0V, Is = -1.7A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	642	_	pF	
Output Capacitance	Coss	_	65	_	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance	C _{rss}		48	_	pF	
Gate Resistance	Rg		15	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$
Total Gate Charge (VGS = -4.5V)	QG		5.8	_	nC	V _{DS} = -15V, I _D = -6A
Total Gate Charge (V _{GS} = -10V)	Q _G		11.8	_		
Gate-Source Charge	Qgs	_	2.0	_	nC	V _{DS} = -15V, I _D = -6A
Gate-Drain Charge	Q _{GD}	_	2.4	_		
Turn-On Delay Time	td(ON)	_	4.9	_		
Rise Time	tr	_	4.7	_	ns	V _{DS} = -15V, V _{GS} = -10V,
Turn-Off Delay Time	tD(OFF)	_	35.2	_	115	$I_D = -1A$, $R_G = 6.0\Omega$
Fall Time	tF		18.2	_		

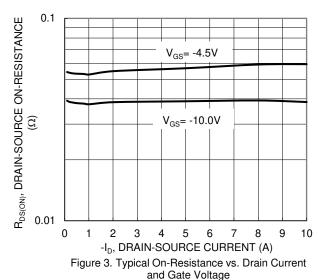
5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate. Notes:

^{6.} Pulse width ≤10μS, Duty Cycle ≤1%.
7. Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to production testing.







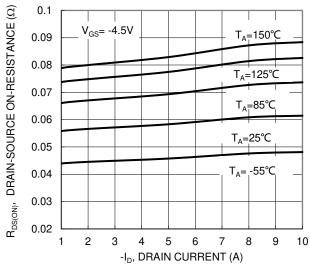


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

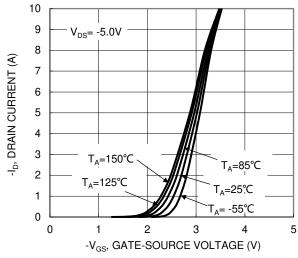


Figure 2. Typical Transfer Characteristic

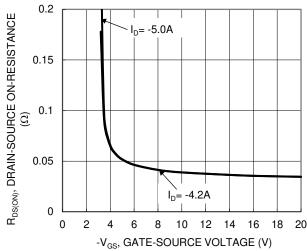


Figure 4. Typical Transfer Characteristic

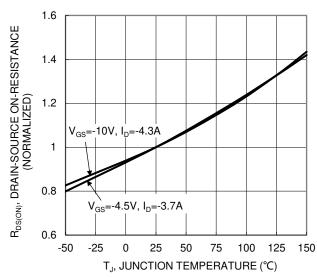


Figure 6. On-Resistance Variation with Temperature



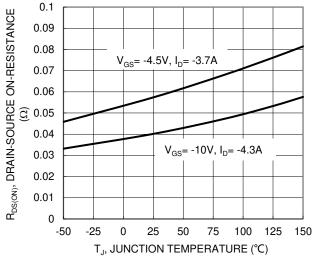


Figure 7. On-Resistance Variation with Temperature

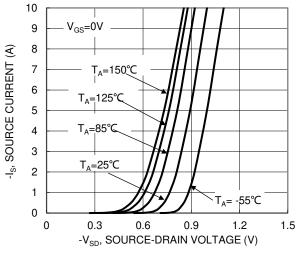
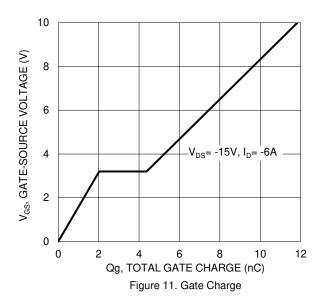


Figure 9. Diode Forward Voltage vs. Current



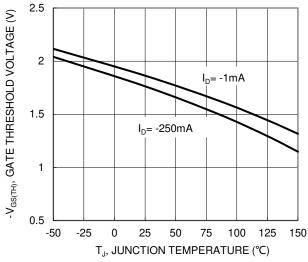
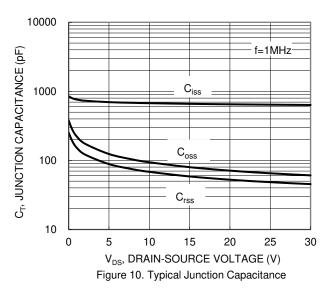


Figure 8. Gate Threshold Variation vs. Junction Temperature



100 $R_{\text{DS}(\text{ON})}$ Limited =100µs ID, DRAIN CURRENT (A) 10 1 $T_{J,(MAX)}$ =150°C 0.1 P_w=100ms Single Pulse DUT on 1*MRP board P_w=10ms $V_{GS} = -10V$ 0.01 0.1 10 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area



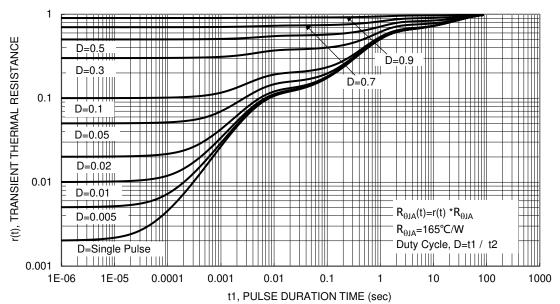


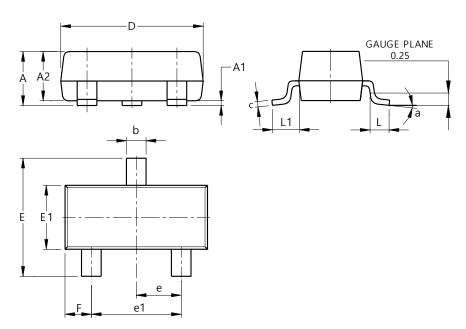
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23 (Standard)

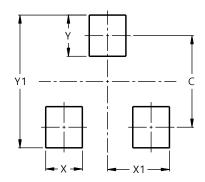


SOT23 (Standard)							
Dim	Min	Max	Тур				
Α	0.90	1.15	1.025				
A 1	0.00	0.10	0.05				
A2	0.85	1.10	0.975				
b	0.30	0.51	0.40				
С	0.080	0.202	0.11				
D	2.80	3.00	2.90				
Е	2.25	2.55	2.40				
E1	1.20	1.40	1.30				
е	0.89	1.03	0.915				
e1	1.78	2.05	1.83				
F	0.40	0.60	0.535				
L1	0.45	0.61	0.55				
L	0.25	0.55	0.40				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23 (Standard)



Dimensions	Value (in mm)			
С	2.0			
Х	0.8			
X1	1.35			
Y	0.9			
V1	2.0			



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